

WHAT IS CLAIMED IS:

1. A stacked small memory card to be set in an electric device, comprising :

A upper memory card includes a first substrate, at least one memory chip, a first heat sink, and a first glue layer, the first substrate formed with an upper surface and a lower surface, the upper surface formed with a plurality of
5 connected points, a plurality of golden fingers electrically connected to the plurality of connected points and a plurality of the through holes, which filled with metal, penetrated the upper surface to the lower surface, at least one memory chip, each of which is mounted on the upper surface of the first substrate,
10 electrically connected to the connected points of the first substrate, the first heat sink, which is mounted on the lower surface of the first substrate, contacted with the metal, which is filled within the through holes, the first glue layer coated the memory chip, the top memory card is used to arranged in the electric device, so that, the golden fingers may be electrically connected to the electric device; and

15 A lower memory card includes a second substrate, at least one memory chip, a second heat sink, and a second glue layer, the second substrate formed with an upper surface and a lower surface, the lower surface formed with a plurality of connected points, a plurality of golden fingers electrically connected to the connected points and a plurality of through holes, which filled with metal,
20 penetrated the upper surface to the lower surface, the memory chip, which is mounted on the lower surface of the second substrate, electrically connected to the connected points of the second substrate, the second heat sink being mounted on

the upper surface of the second substrate, contacted with the metal, which is filled within the through holes, the second glue layer coated the memory chip, which is used to arrange in the electric device, so that, the golden fingers of the second substrate may be electrically connected to the electric device, the first heat sink of
5 the top memory card being mounted on the second heat sink of the bottom memory card.

2. The stacked small memory card according to claim 1, wherein the memory chip of the top memory card electrically connects to the plurality of the connected points of the first substrate via a plurality of wires.

10 3. The stacked small memory card according to claim 1, wherein the metal is filled within the each of through holes of the first substrate is copper.

4. The stacked small memory card according to claim 1, wherein the first heat sink is made of copper or aluminum.

15 5. The stacked small memory card according to claim 1, wherein the memory chip of the bottom memory card electrically connects to the connected points of the second substrate via a plurality of wires.

6. The stacked small memory card according to claim 1, wherein the metal, which is filled within the though holes of the second substrate, is cooper.

20 7. The stacked small memory card according to claim 1, wherein the second heat sink may be cooper or aluminum.